

< Multi : 18.00% - 19.40% >

Dimension 156 mm x 156 mm ± 0.5 mm
 Wafer Thickness 200µm ± 30µm
 180µm + 30µm / -20µm

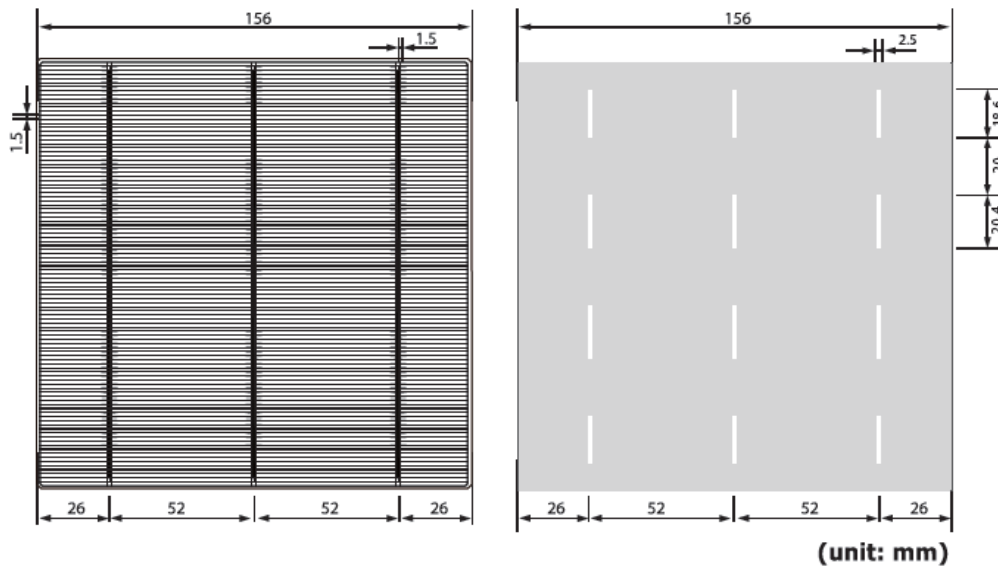
Front(-) Three 1.5 mm wide bus bars (silver) with distance 52 mm, acid texturized surface with blue silicon nitride AR coating.

Back(+) 2.5 mm wide silver/aluminum soldering pads, aluminum local back surface field.

Efficiency code	1800	1820	1840	1860	1880	1900	1920	1940
Efficiency (%)	18.0	18.2	18.4	18.6	18.8	19.0	19.2	19.4
Pmax (W)	4.380	4.429	4.478	4.526	4.575	4.624	4.673	4.721
Voc (V)	0.646	0.647	0.648	0.649	0.651	0.651	0.653	0.653
Isc (A)	8.720	8.801	8.874	8.948	9.001	9.071	9.120	9.210
Vmp (V)	0.549	0.551	0.554	0.556	0.560	0.563	0.566	0.569
Imp (A)	7.979	8.034	8.088	8.141	8.170	8.213	8.254	8.297

*Data under standard testing conditions (STC): 1,000W/m², AM1.5, 25°C, Pmax: Positive power tolerance.

Voltage -2.08 mV/K
 Current +4.58 mA/K
 Power -0.40 %/K



(Cell Efficiency 19.2 %)

